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#### What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

#### Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

#### Details

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	16MHz
Connectivity	I <sup>2</sup> C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	50
Program Memory Size	16KB (8K x 16)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	454 x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	A/D 12x10b
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	68-LCC (J-Lead)
Supplier Device Package	68-PLCC (24.23x24.23)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic17c752-16i-l

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

## 1.0 OVERVIEW

This data sheet covers the PIC17C7XX group of the PIC17CXXX family of microcontrollers. The following devices are discussed in this data sheet:

- PIC17C752
- PIC17C756A
- PIC17C762
- PIC17C766

The PIC17C7XX devices are 68/84-pin, EPROM based members of the versatile PIC17CXXX family of low cost, high performance, CMOS, fully static, 8-bit microcontrollers.

All PIC<sup>®</sup> microcontrollers employ an advanced RISC architecture. The PIC17CXXX has enhanced core features, 16-level deep stack, and multiple internal and external interrupt sources. The separate instruction and data buses of the Harvard architecture allow a 16-bit wide instruction word with a separate 8-bit wide data path. The two stage instruction pipeline allows all instructions to execute in a single cycle, except for program branches (which require two cycles). A total of 58 instructions (reduced instruction set) are available. Additionally, a large register set gives some of the architectural innovations used to achieve a very high performance. For mathematical intensive applications, all devices have a single cycle 8 x 8 Hardware Multiplier.

PIC17CXXX microcontrollers typically achieve a 2:1 code compression and a 4:1 speed improvement over other 8-bit microcontrollers in their class.

PIC17C7XX devices have up to 902 bytes of RAM and 66 I/O pins. In addition, the PIC17C7XX adds several peripheral features, useful in many high performance applications, including:

- Four timer/counters
- Four capture inputs
- Three PWM outputs
- Two independent Universal Synchronous Asynchronous Receiver Transmitters (USARTs)
- An A/D converter (multi-channel, 10-bit resolution)
- A Synchronous Serial Port (SPI and I<sup>2</sup>C w/ Master mode)

These special features reduce external components, thus reducing cost, enhancing system reliability and reducing power consumption.

There are four oscillator options, of which the single pin RC oscillator provides a low cost solution, the LF oscillator is for low frequency crystals and minimizes power consumption, XT is a standard crystal and the EC is for external clock input.

The SLEEP (power-down) mode offers additional power saving. Wake-up from SLEEP can occur through several external and internal interrupts and device RESETS.

A highly reliable Watchdog Timer with its own on-chip RC oscillator provides protection against software malfunction.

There are four configuration options for the device operational mode:

- Microprocessor
- Microcontroller
- Extended microcontroller
- Protected microcontroller

The microprocessor and extended microcontroller modes allow up to 64K-words of external program memory.

The device also has Brown-out Reset circuitry. This allows a device RESET to occur if the device VDD falls below the Brown-out voltage trip point (BVDD). The chip will remain in Brown-out Reset until VDD rises above BVDD.

A UV erasable, CERQUAD packaged version (compatible with PLCC), is ideal for code development, while the cost-effective One-Time-Programmable (OTP) version is suitable for production in any volume.

The PIC17C7XX fits perfectly in applications that require extremely fast execution of complex software programs. These include applications ranging from precise motor control and industrial process control to automotive, instrumentation, and telecom applications.

The EPROM technology makes customization of application programs (with unique security codes, combinations, model numbers, parameter storage, etc.) fast and convenient. Small footprint package options (including die sales) make the PIC17C7XX ideal for applications with space limitations that require high performance.

High speed execution, powerful peripheral features, flexible I/O, and low power consumption all at low cost make the PIC17C7XX ideal for a wide range of embedded control applications.

## 1.1 Family and Upward Compatibility

The PIC17CXXX family of microcontrollers have architectural enhancements over the PIC16C5X and PIC16CXX families. These enhancements allow the device to be more efficient in software and hardware requirements. Refer to Appendix A for a detailed list of enhancements and modifications. Code written for PIC16C5X or PIC16CXX can be easily ported to PIC17CXXX devices (Appendix B).

## 1.2 Development Support

The PIC17CXXX family is supported by a full featured macro assembler, a software simulator, an in-circuit emulator, a universal programmer, a "C" compiler and fuzzy logic support tools. For additional information, see Section 19.0.

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## 7.0 MEMORY ORGANIZATION

There are two memory blocks in the PIC17C7XX; program memory and data memory. Each block has its own bus, so that access to each block can occur during the same oscillator cycle.

The data memory can further be broken down into General Purpose RAM and the Special Function Registers (SFRs). The operation of the SFRs that control the "core" are described here. The SFRs used to control the peripheral modules are described in the section discussing each individual peripheral module.

## 7.1 Program Memory Organization

PIC17C7XX devices have a 16-bit program counter capable of addressing a 64K x 16 program memory space. The RESET vector is at 0000h and the interrupt vectors are at 0008h, 0010h, 0018h, and 0020h (Figure 7-1).

### 7.1.1 PROGRAM MEMORY OPERATION

The PIC17C7XX can operate in one of four possible program memory configurations. The configuration is selected by configuration bits. The possible modes are:

- Microprocessor
- Microcontroller
- Extended Microcontroller
- Protected Microcontroller

The **Microcontroller** and **Protected Microcontroller** modes only allow internal execution. Any access beyond the program memory reads unknown data. The Protected Microcontroller mode also enables the code protection feature.

The **Extended Microcontroller** mode accesses both the internal program memory, as well as external program memory. Execution automatically switches between internal and external memory. The 16-bits of address allow a program memory range of 64K-words.

The **Microprocessor** mode only accesses the external program memory. The on-chip program memory is ignored. The 16-bits of address allow a program memory range of 64K-words. Microprocessor mode is the default mode of an unprogrammed device.

The different modes allow different access to the configuration bits, test memory and boot ROM. Table 7-1 lists which modes can access which areas in memory. Test Memory and Boot Memory are not required for normal operation of the device. Care should be taken to ensure that no unintended branches occur to these areas.

## FIGURE 7-1:

#### PROGRAM MEMORY MAP AND STACK



## 8.0 TABLE READS AND TABLE WRITES

The PIC17C7XX has four instructions that allow the processor to move data from the data memory space to the program memory space, and vice versa. Since the program memory space is 16-bits wide and the data memory space is 8-bits wide, two operations are required to move 16-bit values to/from the data memory.

The TLWT t, f and TABLWT t, i, f instructions are used to write data from the data memory space to the program memory space. The TLRD t, f and TABLRD t, i, f instructions are used to write data from the program memory space to the data memory space.

The program memory can be internal or external. For the program memory access to be external, the device needs to be operating in Microprocessor or Extended Microcontroller mode.

Figure 8-1 through Figure 8-4 show the operation of these four instructions. The steps show the sequence of operation.

## FIGURE 8-1: TLWT INSTRUCTION OPERATION



## FIGURE 8-2: TABLWT INSTRUCTION OPERATION



Example 9-4 shows the sequence to do a 16 x 16 signed multiply. Equation 9-2 shows the algorithm used. The 32-bit result is stored in four registers, RES3:RES0. To account for the sign bits of the arguments, each argument pairs most significant bit (MSb) is tested and the appropriate subtractions are done.

#### EQUATION 9-2: 16 x 16 SIGNED MULTIPLICATION ALGORITHM

RES3:RES0	
$= ARG1H:ARG1L \bullet ARG2H:ARG2L$	
$= (ARG1H \bullet ARG2H \bullet 2^{16})$	+
$(ARG1H \bullet ARG2L \bullet 2^8)$	+
$(ARG1L \bullet ARG2H \bullet 2^8)$	+
$(ARG1L \bullet ARG2L)$	+
$(-1 \bullet ARG2H < 7 > \bullet ARG1H:ARG1L \bullet 2^{16})$	+
$(-1 \bullet ARG1H < 7 > \bullet ARG2H:ARG2L \bullet 2^{16})$	

#### EXAMPLE 9-4: 16 x 16 SIGNED MULTIPLY ROUTINE

	MOVFP	ARG1L, WREG		
	MULWF	ARG2L	;	ARG1L * ARG2L ->
			;	PRODH: PRODL
	MOVPF	PRODH, RES1	;	
	MOVPF	PRODL. RESO	;	
		,	'	
'	MOVED	ARGIH WREG		
	MULWE	ARGIN, WREG		APC14 * APC24 ->
	MODWL	AKGZII	΄.	
	MOUDE		i	PRODH: PRODE
	MOVPF	PRODE, RESS	;	
	MOVPF	PRODL, RESZ	;	
;	MOLIED			
	MOVEP	ARGIL, WREG		
	MOTME	ARG2H	;	ARGIL * ARG2H ->
			;	PRODH: PRODL
	MOVFP	PRODL, WREG	;	
	ADDWF	RES1, F	;	Add cross
	MOVFP	PRODH, WREG	;	products
	ADDWFC	RES2, F	;	
	CLRF	WREG, F	;	
	ADDWFC	RES3, F	;	
;				
	MOVFP	ARG1H, WREG	;	
	MULWF	ARG2L	;	ARG1H * ARG2L ->
			;	PRODH: PRODL
	MOVFP	PRODL, WREG	;	
	ADDWF	RES1, F	;	Add cross
	MOVFP	PRODH, WREG	;	products
	ADDWFC	RES2, F	;	
	CLRF	WREG, F	;	
	ADDWFC	RES3, F	;	
;				
	BTFSS	ARG2H, 7	;	ARG2H:ARG2L neg?
	GOTO	SIGN_ARG1	;	no, check ARG1
	MOVFP	ARG1L, WREG	;	
	SUBWF	RES2	;	
	MOVFP	ARG1H, WREG	;	
	SUBWFB	RES3		
;				
SI	GN ARG1			
	BTFSS	ARG1H, 7	;	ARG1H:ARG1L neg?
	GOTO	CONT CODE	;	no, done
	MOVFP	ARG2L, WREG	;	
	SUBWF	RES2	;	
	MOVFP	ARG2H, WREG	;	
	SUBWFB	RES3		
;				
CO	NT CODE			
	•			





## TABLE 10-9: PORTE FUNCTIONS

Name	Bit	Buffer Type	Function
RE0/ALE	bit0	TTL	Input/output or system bus Address Latch Enable (ALE) control pin.
RE1/OE	bit1	TTL	Input/output or system bus Output Enable ( $\overline{OE}$ ) control pin.
RE2/WR	bit2	TTL	Input/output or system bus Write (WR) control pin.
RE3/CAP4	bit3	ST	Input/output or Capture4 input pin.

Legend: TTL = TTL input, ST = Schmitt Trigger input

## TABLE 10-10: REGISTERS/BITS ASSOCIATED WITH PORTE

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	MCLR, WDT
15h, Bank 1	PORTE	—	—	_	—	RE3/CAP4	RE2/WR	RE1/OE	RE0/ALE	xxxx	uuuu
14h, Bank 1	DDRE	Data Dire	ction Regis	ter for PORT	ΓE					1111	1111
14h, Bank 7	CA4L	Capture4	Low Byte							xxxx xxxx	uuuu uuuu
15h, Bank 7	CA4H	Capture4 High Byte							xxxx xxxx	uuuu uuuu	
16h, Bank 7	TCON3	—	CA4OVF	CA30VF	CA4ED1	CA4ED0	CA3ED1	CA3ED0	PWM3ON	-000 0000	-000 0000

Legend: x = unknown, u = unchanged, - = unimplemented, read as '0'. Shaded cells are not used by PORTE.

#### 10.10.2 SUCCESSIVE OPERATIONS ON I/O PORTS

The actual write to an I/O port happens at the end of an instruction cycle, whereas for reading, the data must be valid at the beginning of the instruction cycle (Figure 10-20). Therefore, care must be exercised if a write followed by a read operation is carried out on the same I/O port. The sequence of instructions should be such to allow the pin voltage to stabilize (load dependent) before executing the instruction that reads the values on that I/O port. Otherwise, the previous state of that pin may be read into the CPU, rather than the "new" state. When in doubt, it is better to separate these instructions with a NOP, or another instruction not accessing this I/O port.

Figure 10-21 shows the I/O model which causes this situation. As the effective capacitance (C) becomes larger, the rise/fall time of the I/O pin increases. As the device frequency increases, or the effective capacitance increases, the possibility of this subsequent PORTx read-modify-write instruction issue increases. This effective capacitance includes the effects of the board traces.

The best way to address this is to add a series resistor at the I/O pin. This resistor allows the I/O pin to get to the desired level before the next instruction.

The use of NOP instructions between the subsequent PORTx read-modify-write instructions, is a lower cost solution, but has the issue that the number of NOP instructions is dependent on the effective capacitance C and the frequency of the device.



## FIGURE 10-20: SUCCESSIVE I/O OPERATION

#### FIGURE 10-21: I/O CONNECTION ISSUES



	R-0	R-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	CA2OVF	CA10VF	PWM2ON	PWM10N	CA1/PR3	TMR3ON	TMR2ON	TMR10N
	bit 7							bit 0
bit 7	<b>CA2OVF</b> : 1 This bit in (CA2H:CA unread caj the capture 1 = Overfle 0 = No ove	Capture2 Ov idicates that .2L) before the pture value ( e register with ow occurred erflow occurred	verflow Status the capture he next capt last capture I th the TMR3 on Capture2 red on Captu	s bit value had ure event oc before overfl value until th register re2 register	not been re ccurred. The low). Subseq ne capture re	ad from the capture regi uent capture gister has be	e capture re ister retains events will r een read (bot	gister pair the oldest not update th bytes).
bit 6	CA1OVF: This bit ind CA1H:PR3 est unreac update the bytes). 1 = Overfile 0 = No ove	Capture1 Ov licates that th 3L/CA1L), be d capture va capture reg ow occurred erflow occurr	verflow Status ne capture va ifore the next lue (last cap jister with the on Capture1 red on Captu	s bit alue had not capture eve oture before TMR3 valu register re1 register	been read fro nt occurred. overflow). S e until the ca	om the captur The capture i Subsequent c apture registe	re register pa register retai apture even ar has been i	air (PR3H/ ns the old- its will not read (both
bit 5	<b>PWM2ON</b> : 1 = PWM2 (The R 0 = PWM2 (The R	: PWM2 On I is enabled :B3/PWM2 p is disabled :B3/PWM2 p	bit in ignores the in uses the s	e state of the	) DDRB<3> I ∙DRB<3> bit	bit.) for data direc	ction.)	
bit 4	<b>PWM1ON</b> : 1 = PWM1 (The R 0 = PWM1 (The R	: PWM1 On I is enabled B2/PWM1 p is disabled B2/PWM1 p	oit in ignores the in uses the s	e state of the	∋ DDRB<2> I ∙DRB<2> bit	bit.) for data direc	ction.)	
bit 3	CA1/PR3: 1 =Enable (PR3H 0 =Enable (PR3H	CA1/PR3 Re s Capture1 /CA1H:PR3L s the Period /CA1H:PR3L	egister Mode _/CA1L is the ⊧register ∟/CA1L is the	<ul> <li>Select bit</li> <li>Capture1 re</li> <li>Period regi</li> </ul>	əgister. Time ster for Time	r3 runs witho r3.)	ut a period r	egister.)
bit 2	<b>TMR3ON</b> : 1 = Starts 0 = Stops	Timer3 On b Timer3 Timer3	oit					
bit 1	<b>TMR2ON</b> : This bit con (T16 is set 1 = Starts 0 = Stops	Timer2 On to ntrols the inc i), TMR2ON Timer2 (mus Timer2	bit rementing of must be set. t be enabled	the TMR2 re This allows if the T16 b	egister. Whei the MSB of t it (TCON1<3	n TMR2:TMR he timer to in >) is set)	<pre>{1 form the 1 icrement.</pre>	6-bit timer
bit 0	TMR1ON:           When T16           1 = Starts           0 = Stops           When T16           1 = Starts           0 = Stops	Timer1 On b is set (in 16- 16-bit TMR2 16-bit TMR2 is clear (in 8 8-bit Timer1 8-bit Timer1	oit <u>-bit Timer mo</u> :TMR1 :TMR1 <u>3-bit Timer m</u>	<u>ode):</u> ode:				
	Legend:							

## REGISTER 13-2: TCON2 REGISTER (ADDRESS: 17h, BANK 3)

### 13.1.3.1 PWM Periods

The period of the PWM1 output is determined by Timer1 and its period register (PR1). The period of the PWM2 and PWM3 outputs can be individually software configured to use either Timer1 or Timer2 as the timebase. For PWM2, when TM2PW2 bit (PW2DCL<5>) is clear, the time base is determined by TMR1 and PR1 and when TM2PW2 is set, the time base is determined by Timer2 and PR2. For PWM3, when TM2PW3 bit (PW3DCL<5>) is clear, the time base is determined by TMR1 and PR1, and when TM2PW3 is set, the time base is determined by Timer2 and PR2.

Running two different PWM outputs on two different timers allows different PWM periods. Running all PWMs from Timer1 allows the best use of resources by freeing Timer2 to operate as an 8-bit timer. Timer1 and Timer2 cannot be used as a 16-bit timer if any PWM is being used.

The PWM periods can be calculated as follows:

period of PWM1 =  $[(PR1) + 1] \times 4TOSC$ 

period of PWM2 =  $[(PR1) + 1] \times 4TOSC$  or  $[(PR2) + 1] \times 4TOSC$ 

period of PWM3 = 
$$[(PR1) + 1] \times 4TOSC$$
 or  
 $[(PR2) + 1] \times 4TOSC$ 

The duty cycle of PWMx is determined by the 10-bit value DCx<9:0>. The upper 8-bits are from register PWxDCH and the lower 2-bits are from PWxDCL<7:6> (PWxDCH:PWxDCL<7:6>). Table 13-4 shows the maximum PWM frequency (FPWM), given the value in the period register.

The number of bits of resolution that the PWM can achieve depends on the operation frequency of the device as well as the PWM frequency (FPWM).

Maximum PWM resolution (bits) for a given PWM frequency:

$$= \frac{\log\left(\frac{FOSC}{FPWM}\right)}{\log\left(2\right)} \quad \text{bits}$$

where: FPWM = 1 / period of PWM

The PWMx duty cycle is as follows:

PWMx Duty Cycle =  $(DCx) \times TOSC$ 

where DCx represents the 10-bit value from PWxDCH:PWxDCL.

If DCx = 0, then the duty cycle is zero. If PRx = PWxDCH, then the PWM output will be low for one to four Q-clocks (depending on the state of the PWxDCL<7:6> bits). For a duty cycle to be 100%, the PWxDCH value must be greater then the PRx value.

The duty cycle registers for both PWM outputs are double buffered. When the user writes to these registers, they are stored in master latches. When TMR1 (or TMR2) overflows and a new PWM period begins, the master latch values are transferred to the slave latches and the PWMx pin is forced high.

Note:	For PW1DCH, PW1DCL, PW2DCH,
	PW2DCL, PW3DCH and PW3DCL regis-
	ters, a write operation writes to the "master
	latches", while a read operation reads the
	"slave latches". As a result, the user may
	not read back what was just written to the
	duty cycle registers (until transferred to
	slave latch).

The user should also avoid any "read-modify-write" operations on the duty cycle registers, such as: ADDWF PW1DCH. This may cause duty cycle outputs that are unpredictable.

TABLE 13-4:	PWM FREQUENCY vs.
	<b>RESOLUTION AT 33 MHz</b>

PWM		Fre	quency	(kHz)	
Frequency	32.2	64.5	90.66	128.9	515.6
PRx Value	0xFF	0x7F	0x5A	0x3F	0x0F
High Resolution	10-bit	9-bit	8.5-bit	8-bit	6-bit
Standard Resolution	8-bit	7-bit	6.5-bit	6-bit	4-bit

13.1.3.2 PWM INTERRUPTS

The PWM modules make use of the TMR1 and/or TMR2 interrupts. A timer interrupt is generated when TMR1 or TMR2 equals its period register and on the following increment is cleared to zero. This interrupt also marks the beginning of a PWM cycle. The user can write new duty cycle values before the timer rollover. The TMR1 interrupt is latched into the TMR1IF bit and the TMR2 interrupt is latched into the TMR2IF bit. These flags must be cleared in software.







The ADRESH:ADRESL registers contain the 10-bit result of the A/D conversion. When the A/D conversion is complete, the result is loaded into this A/D result register pair, the GO/DONE bit (ADCON0<2>) is cleared and A/D interrupt flag bit, ADIF is set. The block diagrams of the A/D module are shown in Figure 16-1.

After the A/D module has been configured as desired, the selected channel must be acquired before the conversion is started. The analog input channels must have their corresponding DDR bits selected as inputs. To determine sample time, see Section 16.1. After this acquisition time has elapsed, the A/D conversion can be started. The following steps should be followed for doing an A/D conversion:

- 1. Configure the A/D module:
  - a) Configure analog pins/voltage reference/ and digital I/O (ADCON1)
  - b) Select A/D input channel (ADCON0)
  - c) Select A/D conversion clock (ADCON0)
  - d) Turn on A/D module (ADCON0)



- 2. Configure A/D interrupt (if desired):
  - a) Clear ADIF bit
  - b) Set ADIE bit
  - c) Clear GLINTD bit
- 3. Wait the required acquisition time.
- 4. Start conversion:
  - a) Set GO/DONE bit (ADCON0)
- 5. Wait for A/D conversion to complete, by either:
  - a) Polling for the GO/DONE bit to be cleared OR
  - b) Waiting for the A/D interrupt
- 6. Read A/D Result register pair (ADRESH:ADRESL), clear bit ADIF, if required.
- 7. For next conversion, go to step 1 or step 2, as required. The A/D conversion time per bit is defined as TAD. A minimum wait of 2TAD is required before next acquisition starts.



## 16.7 A/D Accuracy/Error

In systems where the device frequency is low, use of the A/D RC clock is preferred. At moderate to high frequencies, TAD should be derived from the device oscillator.

The absolute accuracy specified for the A/D converter includes the sum of all contributions for quantization error, integral error, differential error, full scale error, offset error, and monotonicity. It is defined as the maximum deviation from an actual transition versus an ideal transition for any code. The absolute error of the A/D converter is specified at <  $\pm$ 1 LSb for VDD = VREF (over the device's specified operating range). However, the accuracy of the A/D converter will degrade as VREF diverges from VDD.

For a given range of analog inputs, the output digital code will be the same. This is due to the quantization of the analog input to a digital code. Quantization error is typically  $\pm$  1/2 LSb and is inherent in the analog to digital conversion process. The only way to reduce quantization error is to increase the resolution of the A/D converter or oversample.

Offset error measures the first actual transition of a code versus the first ideal transition of a code. Offset error shifts the entire transfer function. Offset error can be calibrated out of a system or introduced into a system through the interaction of the total leakage current and source impedance at the analog input.

Gain error measures the maximum deviation of the last actual transition and the last ideal transition adjusted for offset error. This error appears as a change in slope of the transfer function. The difference in gain error to full scale error is that full scale does not take offset error into account. Gain error can be calibrated out in software.

Linearity error refers to the uniformity of the code changes. Linearity errors cannot be calibrated out of the system. Integral non-linearity error measures the actual code transition versus the ideal code transition, adjusted by the gain error for each code.

Differential non-linearity measures the maximum actual code width versus the ideal code width. This measure is unadjusted.

The maximum pin leakage current is specified in the Device Data Sheet electrical specification (Table 20-2, parameter #D060).

In systems where the device frequency is low, use of the A/D RC clock is preferred. At moderate to high frequencies, TAD should be derived from the device oscillator. TAD must not violate the minimum and should be minimized to reduce inaccuracies due to noise and sampling capacitor bleed off. In systems where the device will enter SLEEP mode after the start of the A/D conversion, the RC clock source selection is required. In this mode, the digital noise from the modules in SLEEP are stopped. This method gives high accuracy.

## 16.8 Connection Considerations

If the input voltage exceeds the rail values (VSS or VDD) by greater than 0.3V, then the accuracy of the conversion is out of specification.

An external RC filter is sometimes added for antialiasing of the input signal. The R component should be selected to ensure that the total source impedance is kept under the 10 k $\Omega$  recommended specification. Any external components connected (via hi-impedance) to an analog input pin (capacitor, zener diode, etc.) should have very little leakage current at the pin.

## 16.9 Transfer Function

The transfer function of the A/D converter is as follows: the first transition occurs when the analog input voltage (VAIN) equals Analog VREF / 1024 (Figure 16-7).

#### FIGURE 16-7: A/D TRANSFER FUNCTION



BSF		Bit Set f				
Synt	ax:	[ <i>label</i> ] E	BSF f,t	)		
Ope	rands:	$0 \le f \le 25$ $0 \le b \le 7$	5			
Ope	ration:	$1 \rightarrow (f < b >$	•)			
Statu	us Affected:	None				
Enco	oding:	1000	0bbb	fff	f	ffff
Des	cription:	Bit 'b' in reg	gister 'f' is	s set.		
Wor	ds:	1				
Cycl	es:	1				
QC	ycle Activity:					
	Q1	Q2	Q	3		Q4
	Decode	Read register 'f'	Proce Dat	ess a	re	Write gister 'f'
<u>Exar</u>	<u>mple</u> : Before Instru FLAG_R	BSF Iction EG = 0x	flag_re	G, 7		
	After Instruct FLAG_R	tion EG = 0x	:8A			

BTF	SC	Bit Test, s	kip if Clear	
Synt	ax:	[label] B	TFSC f,b	
Ope	rands:	$\begin{array}{l} 0 \leq f \leq 255 \\ 0 \leq b \leq 7 \end{array}$	i	
Ope	ration:	skip if (f <b< td=""><td>&gt;) = 0</td><td></td></b<>	>) = 0	
Statu	us Affected:	None		
Enco	oding:	1001	1bbb ff	ff ffff
Deso	cription:	If bit 'b' in re instruction i If bit 'b' is 0,	gister 'f' is 0, th s skipped. then the next i	nen the next
		cution is dis instead, ma instruction.	carded and a $N$ king this a two-	OP is executed
Wor	ds:	1		
Cycl	es:	1(2)		
QC	cle Activity:			
	Q1	Q2	Q3	Q4
	Decode	Read register 'f'	Process Data	No operation
lf ski	Decode	Read register 'f'	Process Data	No operation
lf ski	Decode ip: Q1	Read register 'f' Q2	Process Data Q3	No operation Q4
lf ski	Decode p: Q1 No operation	Read register 'f' Q2 No operation	Process Data Q3 No operation	No operation Q4 No operation
lf ski <u>Exar</u>	Decode p: Q1 No operation mple:	Read register 'f' Q2 No operation HERE E FALSE : TRUE :	Process Data Q3 No operation TFSC FLAC	No operation Q4 No operation
lf ski <u>Exar</u>	Decode p: Q1 No operation mple: Before Instruct PC	Read register 'f' Q2 No operation HERE B FALSE : TRUE : ction = adu	Process Data Q3 No operation TFSC FLAC	No operation Q4 No operation
lf ski <u>Exar</u>	Decode p: Q1 No operation mple: Before Instruct PC After Instructi If FLAG<7 PC	Read register 'f' Q2 No operation HERE E FALSE : TRUE : Ction = add ion 1> = 0; = add	Process Data Q3 No operation TFSC FLAC dress (HERE) dress (TRUE)	No operation Q4 No operation

IORWF	Inclusive OR WREG with f					
Syntax:	[ label ]	IORWF	f,d			
Operands:	$\begin{array}{l} 0 \leq f \leq 255 \\ d \in [0,1] \end{array}$	5				
Operation:	(WREG) .	OR. (f) $\rightarrow$	(dest)			
Status Affected:	Z					
Encoding:	0000	100d	ffff	ffff		
Description:	Inclusive O 'd' is 0, the 'd' is 1, the register 'f'.	R WREG v result is pl result is pl	with regis aced in \ aced bac	ster 'f'. If NREG. If ck in		
Words:	1					
Cycles:	1					
Q Cycle Activity:						
Q1	Q2	Q3		Q4		
Decode	Read register 'f'	Proces Data	s V de:	Vrite to stination		
Example: Before Instruct RESULT WREG After Instructi RESULT WREG	IORWF RJ ction = 0x13 = 0x91 on = 0x13 = 0x93	ESULT, O				

LCA	LCALL Long Call							
Synt	ax:	[ label ]	LCALL	k				
Ope	rands:	$0 \le k \le 25$	5					
Ope	ration:	$\begin{array}{l} PC + 1 \rightarrow \\ k \rightarrow PCL, \end{array}$	PC + 1 $\rightarrow$ TOS; k $\rightarrow$ PCL, (PCLATH) $\rightarrow$ PCH					
State	us Affected:	None						
Enco	oding:	1011	0111	kkkk	kkkk			
Des	cription:	LCALL allows an unconditional subrou- tine call to anywhere within the 64K program memory space. First, the return address (PC + 1) is pushed onto the stack. A 16-bit desti- nation address is then loaded into the program counter. The lower 8-bits of the destination address are embedded in the instruction. The upper 8-bits of PC are loaded from PC high holding latch PCI ATH						
Wor	ds:	1						
Cycl	es:	2	2					
QC	ycle Activity:							
	Q1	Q2	Q3		Q4			
	Decode	Read literal 'k'	Proce Dat	ess a ro	Write egister PCL			
	No operation	No No No operation operation operation						
<u>Exa</u>	<u>mple</u> : Before lostri	MOVLW H MOVPF W LCALL L	IGH(SUE REG, PC OW(SUBF	BROUTII CLATH ROUTINI	NE) E)			
	SUBROUT PC	IINE = 16 $= ?$	-bit Addr	ess				
After Instruction PC = Address (SUBROUTINE)				JTINE)				

MO\	/FP	Move f to	р			MOVLB
Synt	ax:	[ <i>label</i> ] N	/OVFP_f,p	Syntax:		
Ope	rands:	$0 \le f \le 25$	5			Operands:
		$0 \le p \le 31$				Operation:
Ope	ration:	$(f) \to (p)$				Status Affe
Statu	us Affected:	None				Encoding:
Enco	oding:	011p	pppp i	fff	ffff	Descriptior
Deso	Description: Move data from data memory location 'f' to data memory location 'p'. Location 'f' can be anywhere in the 256 byte data space (00h to FFh), while 'p' can be 00h to 1Fh.					
		Either 'p' o special situ	r 'f' can be V ation).	/REG (	(a useful,	Words:
	MOVFP is particularly useful for transfer- ring a data memory location to a periph- eral register (such as the transmit buffer or an I/O port). Both 'f' and 'p' can be indirectly addressed.					Cycles: Q Cycle Ac Q Dec
Wor	ds:	1				
Cycl	es:	1				
QC	ycle Activity:					Example:
	Q1	Q2	Q3		Q4	Before
	Decode	Read register 'f'	Process Data	re	Write gister 'p'	BS After I

Example:	MOVFP	REG1,	REG2
Before Instruc REG1 REG2	tion = =	0x33, 0x11	
After Instruction	n		
REG1	=	0x33,	
REG2	=	0x33	

Move Literal to low nibble in BSR [label] MOVLB k  $0 \leq k \leq 15$  $k \rightarrow (BSR<3:0>)$ ected: None 1011 1000 uuuu kkkk The four-bit literal 'k' is loaded in the ı: Bank Select Register (BSR). Only the low 4-bits of the Bank Select Register are affected. The upper half of the BSR is unchanged. The assembler will encode the "u" fields as '0'. 1 1 ctivity: 1 Q2 Q3 Q4 Write literal ode Read Process literal 'k' Data 'k' to BSR<3:0> MOVLB 5

Before Instruction BSR register	n =	0x22
After Instruction BSR register	=	0x25 (Bank 5)

XOR	RLW	Exclusiv WREG	Exclusive OR Literal with WREG							
Synt	ax:	[ label ]	[label] XORLW k							
Ope	rands:	$0 \le k \le 2$	55							
Ope	ration:	(WREG)	.XOR. k	$\rightarrow$ (WR	REG)					
Statu	us Affected:	Z								
Enco	oding:	1011	0100	kkkk	kkkk					
Des	cription:	The conte with the 8 placed in	The contents of WREG are XOR'ed with the 8-bit literal 'k'. The result is placed in WREG.							
Wor	ds:	1								
Cycl	es:	1								
QC	vcle Activity:									
	Q1	Q2	Q3		Q4					
	Decode	Read literal 'k'	Proce Data	ess a	Write to WREG					
<u>Exar</u>	<u>mple</u> :	XORLW	0xAF							
	Before Instru WREG	iction = 0xB5								
	After Instruct WREG	tion = 0x1A								

XORWF	Exclusive	e OR WF	REG ۱	with	f
Syntax:	[label]	KORWF	f,d		
Operands:	$\begin{array}{l} 0 \leq f \leq 255 \\ d \in [0,1] \end{array}$	5			
Operation:	(WREG) .	XOR. (f)	$\rightarrow$ (d	lest)	
Status Affected:	Z				
Encoding:	0000	110d	fff	f	ffff
Description: Exclusive OR the contents of with register 'f'. If 'd' is 0, the r stored in WREG. If 'd' is 1, the stored back in the register 'f'.				s of W ne re the i 'f'.	VREG sult is result is
Words:	1				
Cycles:	1				
Q Cycle Activity:					
Q1	Q2	Q3			Q4
Decode	Read register 'f'	Proce Data	SS a	W des	rite to tination
Example: XORWF REG, 1					
Before Instruction REG = 0xAF 101 WREG = 0xB5 101					

WIKEO	-	UNDO	1011 0101
After Instruc	tion		
REG	=	0x1A	0001 1010
WREG	=	0xB5	

NOTES:

Param No.	Sym	Characte	ristic	Min	Max	Units	Conditions
110	Tbuf	Bus free time	100 kHz mode	4.7	—	ms	Time the bus must be free
			400 kHz mode	1.3	_	ms	before a new transmission
			1 MHz mode <sup>(1)</sup>	0.5	—	ms	can start
D102	Cb	Bus capacitive loading		—	400	pF	

**Note 1:** Maximum pin capacitance = 10 pF for all  $I^2C$  pins.

2: A fast mode (400 KHz) I<sup>2</sup>C bus device can be used in a standard mode I<sup>2</sup>C bus system, but the parameter # 107 ≥ 250 ns must then be met. This will automatically be the case if the device does not stretch the LOW period of the SCL signal. If such a device does stretch the LOW period of the SCL signal, it must output the next data bit to the SDA line. Parameter #102 + #107 = 1000 + 250 = 1250 ns (for 100 kHz mode) before the SCL line is released.

**3:**  $C_b$  is specified to be from 10-400pF. The minimum specifications are characterized with  $C_b$ =10pF. The rise time spec ( $t_r$ ) is characterized with  $R_p$ = $R_p$  min. The minimum fall time specification ( $t_f$ ) is characterized with  $C_b$ =10pF,and  $R_p$ = $R_p$  max. These are only valid for fast mode operation (VDD=4.5-5.5V) and where the SPM bit (SSPSTAT<7>) =1.)

4: Max specifications for these parameters are valid for falling edge only. Specs are characterized with R<sub>p</sub>=R<sub>p</sub> min and C<sub>b</sub>=400pF for standard mode, 200pF for fast mode, and 10pF for 1MHz mode.

### FIGURE 20-19: USART SYNCHRONOUS TRANSMISSION (MASTER/SLAVE) TIMING



#### TABLE 20-14: USART SYNCHRONOUS TRANSMISSION REQUIREMENTS

Param No.	Sym	Characteristic		Min	Тур†	Max	Units	Conditions
120	TckH2dtV	SYNC XMIT (MASTER & SLAVE)						
		Clock high to data out valid	PIC17 <b>C</b> XXX	—	—	50	ns	
			PIC17LCXXX		-	75	ns	
121	TckRF	Clock out rise time and fall time	PIC17 <b>C</b> XXX	_	—	25	ns	
		(Master mode)	PIC17LCXXX		-	40	ns	
122	TdtRF	Data out rise time and fall time	PIC17CXXX	_	_	25	ns	
			PIC17LCXXX	_	_	40	ns	

† Data in "Typ" column is at 5V, 25°C unless otherwise stated.

# 21.0 PIC17C7XX DC AND AC CHARACTERISTICS

The graphs and tables provided in this section are for design guidance and are not tested nor guaranteed. In some graphs or tables the data presented is outside specified operating range (e.g., outside specified VDD range). This is for information only and devices are ensured to operate properly only within the specified range.

The data presented in this section is a statistical summary of data collected on units from different lots over a period of time.

- Typ or Typical represents the mean of the distribution at 25°C.
- Max or Maximum represents (mean + 3 $\sigma$ ) over the temperature range of -40°C to 85°C.
- Min or Minimum represents (mean  $3\sigma$ ) over the temperature range of -40°C to  $85^{\circ}$ C.
- **Note:** Standard deviation is denoted by sigma ( $\sigma$ ).

### TABLE 21-1: PIN CAPACITANCE PER PACKAGE TYPE

Din Nome	Typical Capacitance (pF)				
	68-pin PLCC	64-pin TQFP			
All pins, except MCLR, VDD, and Vss	10	10			
MCLR pin	20	20			

### FIGURE 21-1: TYPICAL RC OSCILLATOR FREQUENCY vs. TEMPERATURE

